Messrs. Digi-Key

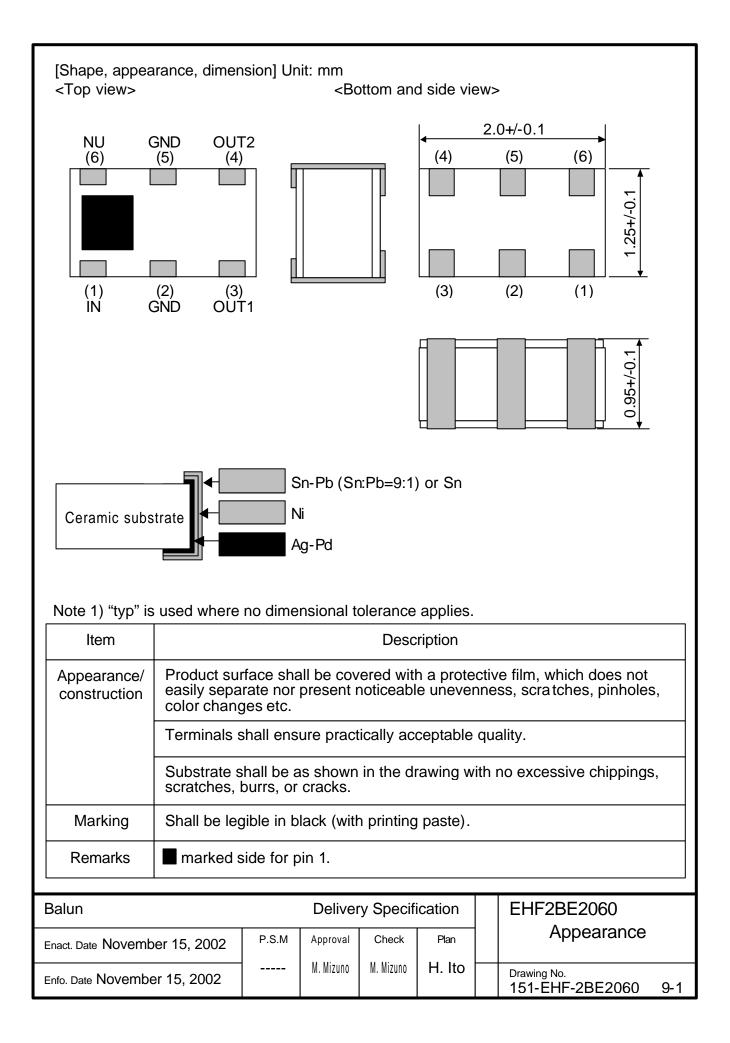
Issue No. : PC-02-066 Date of issue : November 15, 2002 Classification : ■ New □ Change □ Renewal

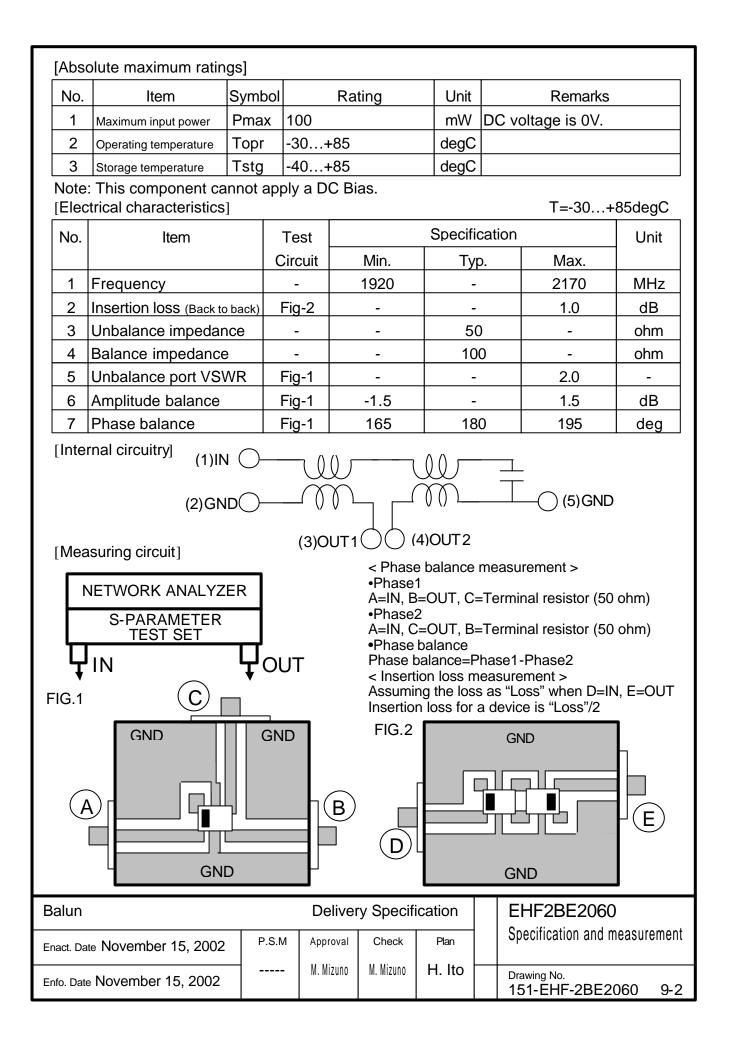
Delivery Specification

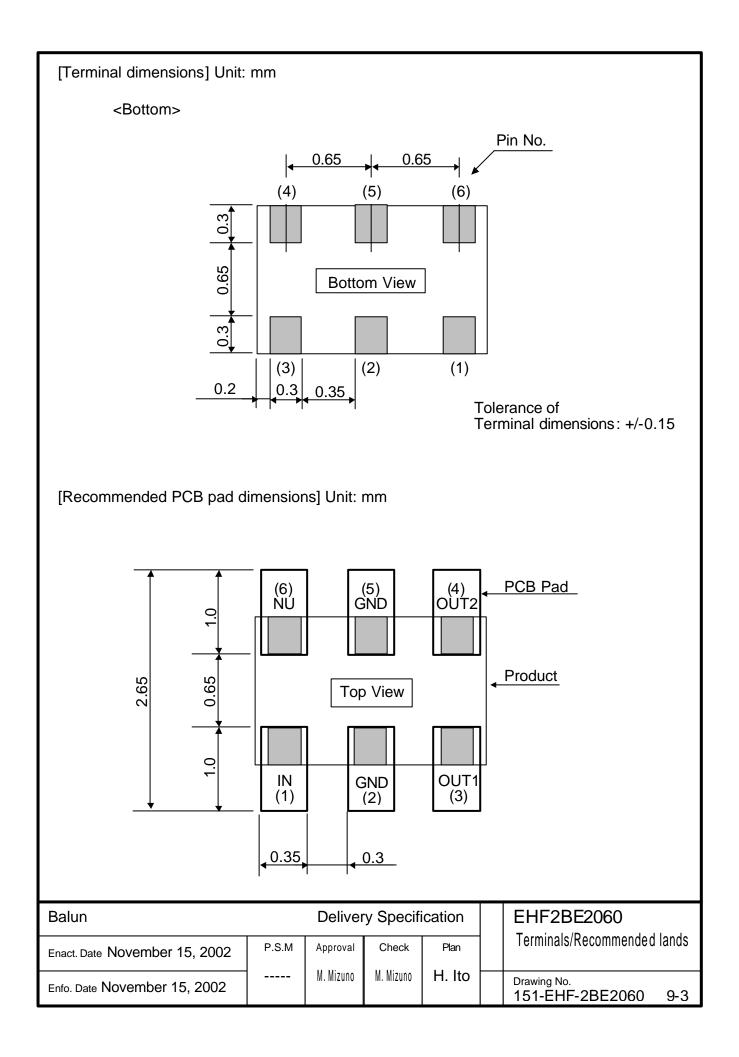
Product Description	: Balun
Product Part Number	: EHF2BE2060
Classification of Spec	: Individual Product Specification
Applications	: Cellular phone
	For other applications, contact the undersigned in advance.
Term of Validity	: November 14, 2007 from the date of issue.

CUSTOMER USE ONLY	Receipt Record#:	
This was certainly received by us. 1(one) copy is being returned to you.	Date of receipt:	
	Received by:	
	Title: Dept.:	

Matsushita Electronic Components Co., Ltd.		
Network Device Company	Prepared by	: H. Ito
Module Strategic Business Unit	Checked by	: M. Mizuno
Engineering Group HFD Team		
992-1 Aiba Ohno-cho Ibi-gun Gifu 501-0598 JAPAN	Authorized by	: M. Mizuno
Tel: +81-0585-36-2322	Title	: Manager of Engineering
Fax: +81-0585-36-2344		







[Quality characteristic	s]	
Test item	Test condition	Judgment criteria
High temperature	+85degC, 1000h	No abnormality shall be observed in
Low temperature	-40degC, 1000h	appearance or
High-temperature high-humidity storage	+60degC, 90%RH, 1000h	electrical characteristics.
Pressure Pot	+121degC, 99%RH, 2.026x10 ⁵ Pa, 100h	characteristics.
Temperature cycling	-40…+85degC, Each 30 min., 200cy	
Vibration	10500Hz, 10G, in each direction of XYZ, 2h30min.	
Impact	100G, 6mS, Half sinusoidal wave, in each direction of XYZ, 3 times	
Shock (Drop)	1.8m, 6 facesx6cy(36 times with 100g Dummy Load)	
Electro static discharge	200pF, 0 ohm, +/-200V, Each 5 times	
Soldering heat resistance	Manual hot gas: 260+/-10degC, 30 sec., 2 times	Over 90% of the terminal
	Soldering iron: 260+/-10degC, 3 sec., 2 times	surface shall be covered with solder.
	Reflow: 260degC peak, 2 times	
Solder ability	Solder bath: 235+/-5degC, 2 sec.	Over 95% of the terminal
	Reflow: 230degC	surface shall be covered with solder.
Board warping	Assemble this component on a PC board with 0.8mm thickness using the recommended soldering condition shown below, and apply a bending force of 3mm warping at a rate of 1mm/sec. 5 seconds and 5 times.	There should not be any cracks in the component or solder joints, no abnormality in electrical characteristics.
Terminal removal	Solder a component on a PC board using the recommended then press the component sideways at 1mm/sec. Destruction lir	
Seating plane co-planarity	Within 0.1mm	
< Recommended sold Diagram1 Shown b degC 250 230 200 170 140	below is a recommended reflow soldering conditio	
	30~60 sec. 60~180 sec.	Time
Balun	Delivery Specification EHF	E2BE2060
Enact. Date November 15, 2	lity Characteristics	
Enfo. Date November 15, 20	^{g No.} EHF-2BE2060 9-4	

[Cautions for use]

- (1) Operating a product over the maximum rating for even a moment may result in a product failure or breakage. Never use a product in such a condition that it may cause a safety problem.
- (2) Opening or short-circuiting the product terminals or inserting a product in the reverse orientation while power is being supplied may cause a breakage. Always avoid such circumstances.
- (3) Operations in a corrosive gas atmosphere or improper environments such as hightemperature, high-humidity or dewy conditions may lead to product performance deterioration, a breakage, a change in appearance etc. Please avoid such conditions, as they are unsafe.
- (4) Always ground the soldering iron or soldering bath used for assembly operation to avoid any excessive voltage applied to a product.
- (5) After soldering with solder bridges, incomplete soldering or in the reverse orientation, supplying power may result in a product breakage. Please confirm the soldered condition before supplying power to the product.
- (6) Excessive stress on the terminals may cause a contact failure or performance deterioration. Please use caution.
- (7) Please provide a fail-safe provision in the product you design by taking any failure of our product into consideration.
- (8) This product does not include a DC-cutting device. Application of a DC voltage between the Balance port and the Unbalance port may cause product deterioration or breakage.
 - * If any question arises about the safety of this product, please contact us immediately with a request for an engineering examination.

[Remarks]

- *1: All of the materials used in this product are those listed as the existing chemical substances based on the "Law for examination and regulation of manufacture of chemical substances".
- *2: The production process of this product does not use any ozone-depleting chemicals (OZC) regulated by the Montreal Protocol.
- *3: Validity of this specification is 5 years from the date of issue, but the validity is considered on going unless any changes are made.

Balun		Delivery Specification				EHF2BE2060		
Enact. Date November 15, 2002	P.S.M	Approval	Check	Plan		Cautions		
Enfo. Date November 15, 2002		M. Mizuno	M. Mizuno	H. Ito		Drawing No. 151-EHF-2BE2060 9-5		

[Packaging materials] 1. Materials 1)

- Embossed carrier tape (Refer to the attachment)
 Top tape: Anti-static

- 3) Packaging box (Refer to the attachment)4) Packaging tape, carrier-securing adhesive tape
- 2. Specification

	•	1						
No.	Item	Condition					Remarks	
1	Reel outer diameter	Refer t	to the att					
2	Reel inner diameter	Refer t	the att					
3	Reel inner width	Refer t	the att	achment				
4	Quantity in a reel	4000 p	oieces/re	el				
5	Taping direction						ling direction ngs facing up)	
6	Top tape attachment position	Top tape	pe attachm e edge mus			5.5mm Embo	tape	Tape breaks force. Min. 10N Top cover tape strength. Min. 10N Tape peel force. 0.11.0N Tape peel angle. 165180degree Reel weight. Max 1500g
7	Label attachment position			Label	─ ► T	ape unreelii	ng direction	Indicated Item Pat No., Lot No. Quantity, Maker Country of Origin
8	Tape leader part and tape ending part	20	part Prod		00~150mm,	Leader	Top tape	
9 Missing products No missing products shall be allowed.								
							84000 pieces/box(Max)	
						BE2060 ging specification 1		
					Drawing N 151-El	^{₦₀.} HF-2BE2060 9-6		

